

Docket No.: M4065.0226/P226  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Patent Application of:  
Tongbi Jiang

Application No.: 09/484,437

Confirmation No.: 9698

Filed: January 18, 2000

Art Unit: 2813

For: Die attach curing method for semiconductor  
device

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Examiner: J. M. Mitchell

**RESPONSE AFTER FINAL ACTION UNDER 37 C.F.R. 1.116**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated March 12, 2007, finally rejecting claims 1-3, 6-9, 11, 12, 14, 16-20, 34, 36, 38-42, 46 and 51, please consider the following remarks.